

EE 466/586
VLSI Design

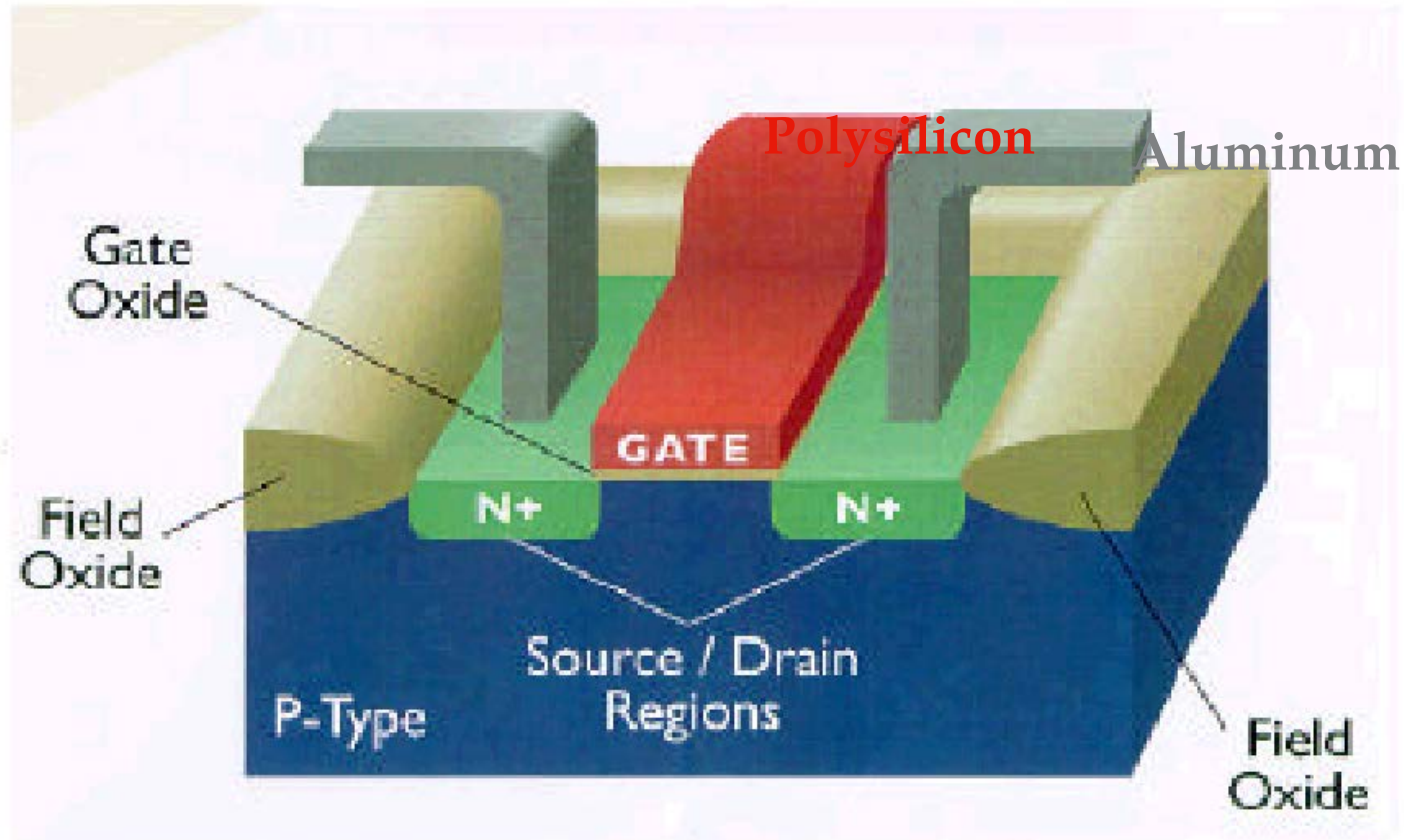
Partha Pande
School of EECS
Washington State University
pande@eecs.wsu.edu

Lecture 2

The MOS Transistor

(Reference: Chapter 2 of Weste and Harris or Chapter 2 of HJS)

The MOS Transistor



Structural Details

□ Channel length L

- Typical values of L today vary from 90nm to 32 nm
- The dimension will continue to scale according to Moore's law

□ Perpendicular to the plane of the figure is the channel width W

- Much larger than the minimum length

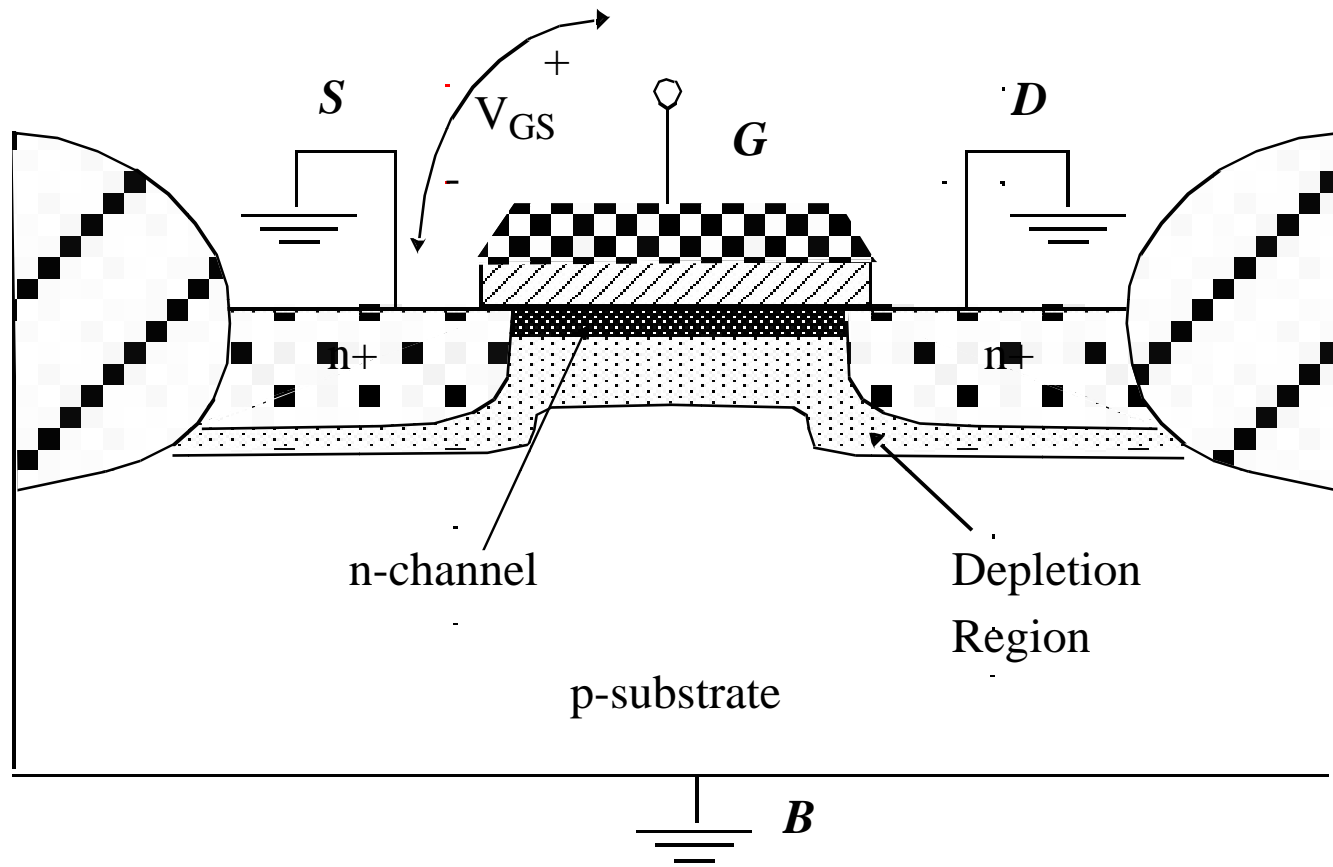
□ Gate oxide thickness t_{ox}

- Around 25 Å

Operational Mechanism

- ❑ We consider a NMOS transistor
- ❑ N+ source and N+ drain regions separated by p-type material
- ❑ The body or substrate, is a single-crystal silicon wafer
- ❑ Suppose, source, drain and body are all tied to ground and a positive voltage applied to the gate
 - A positive gate voltage will tend to draw electrons from the substrate into the channel region
 - A conducting path is created between drain and source
 - Current will flow from drain to source in presence of a voltage difference between the source and the drain
 - The gate voltage needed to initiate formation of a conducting channel is termed as the threshold voltage V_t

Threshold Voltage: Concept

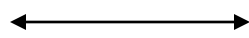


The Threshold Voltage

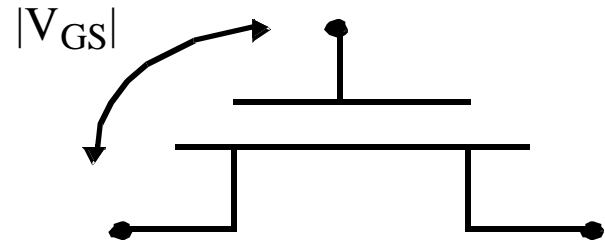
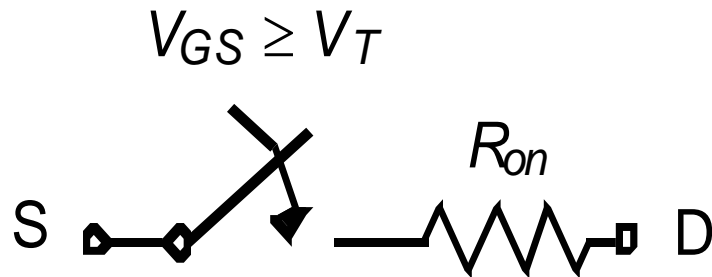
Follow board notes

What is a Transistor?

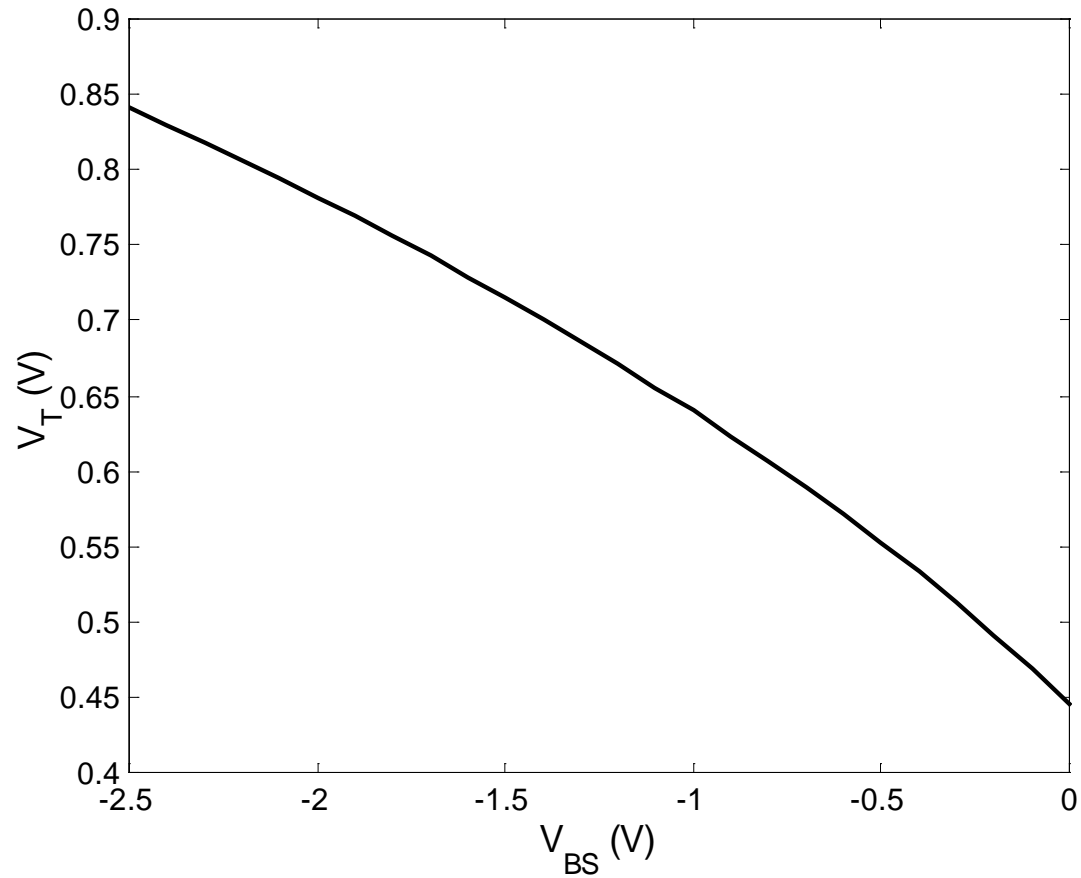
A Switch!



An MOS Transistor



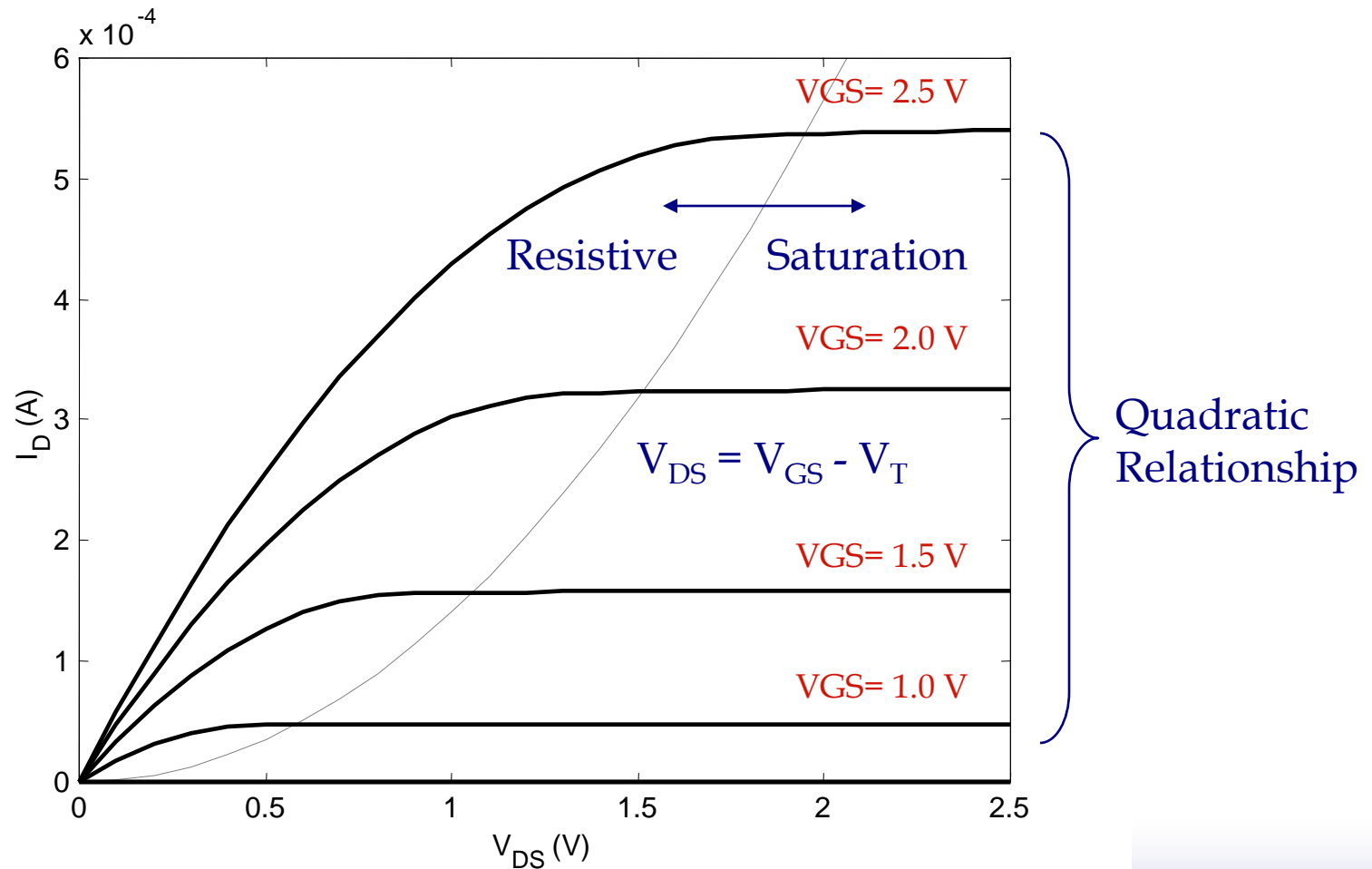
The Body Effect



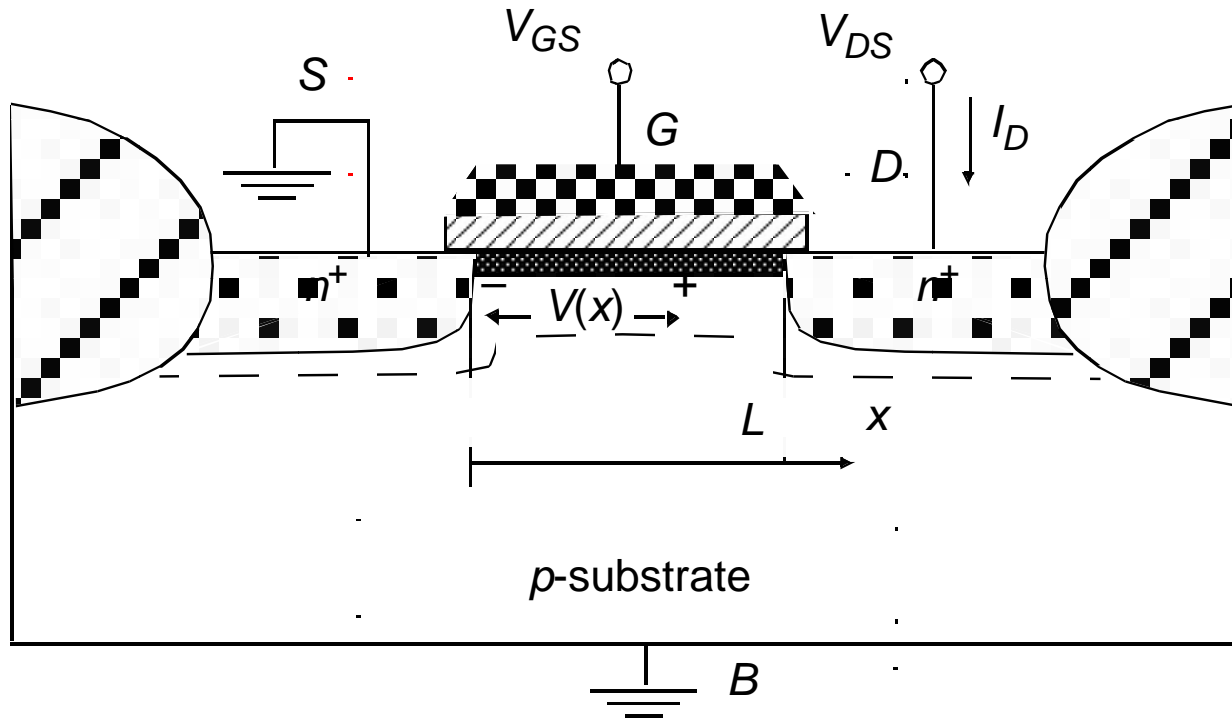
Current-Voltage Relations

- Follow board notes

Current-Voltage Relations

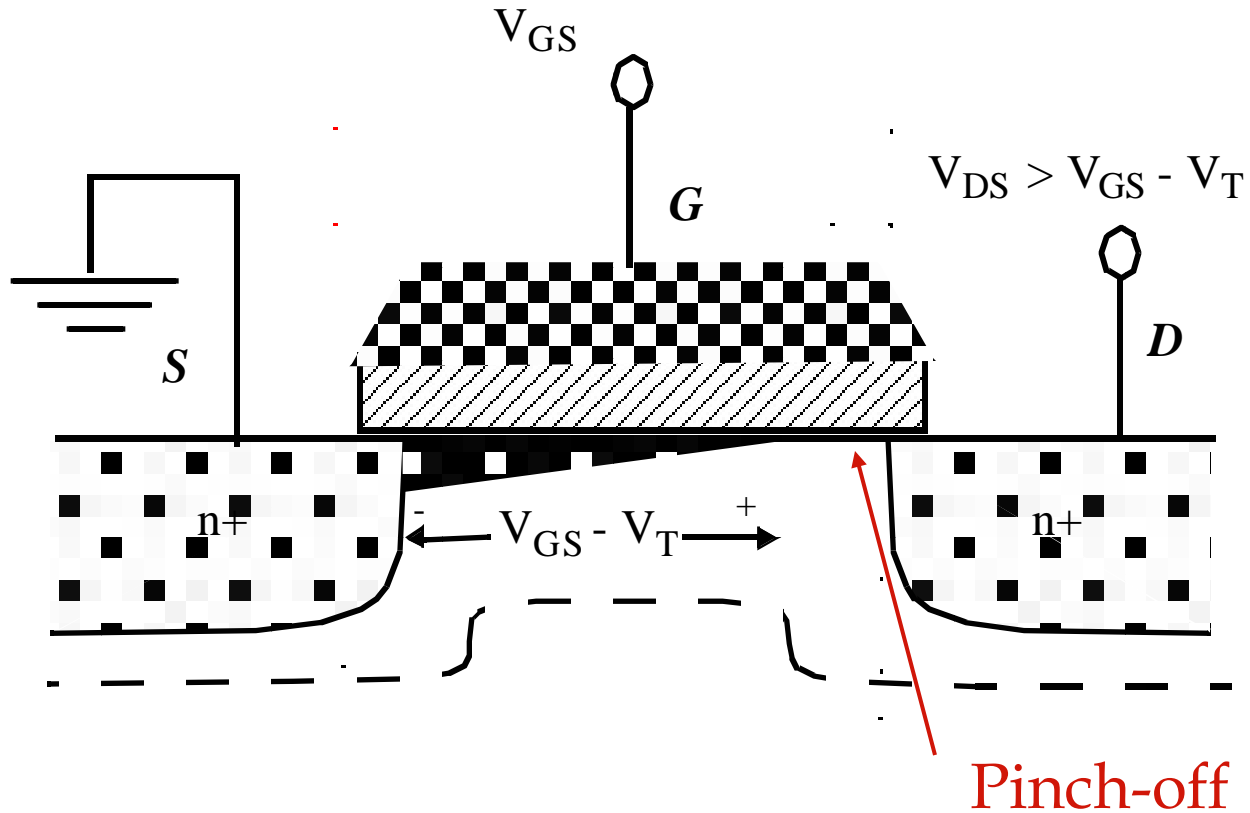


Transistor in Linear



MOS transistor and its bias conditions

Transistor in Saturation

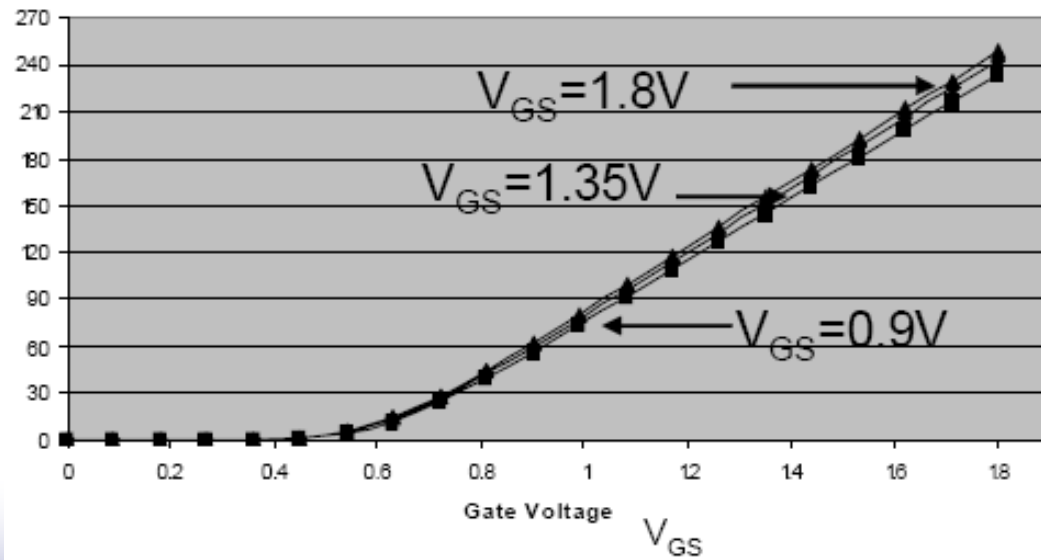
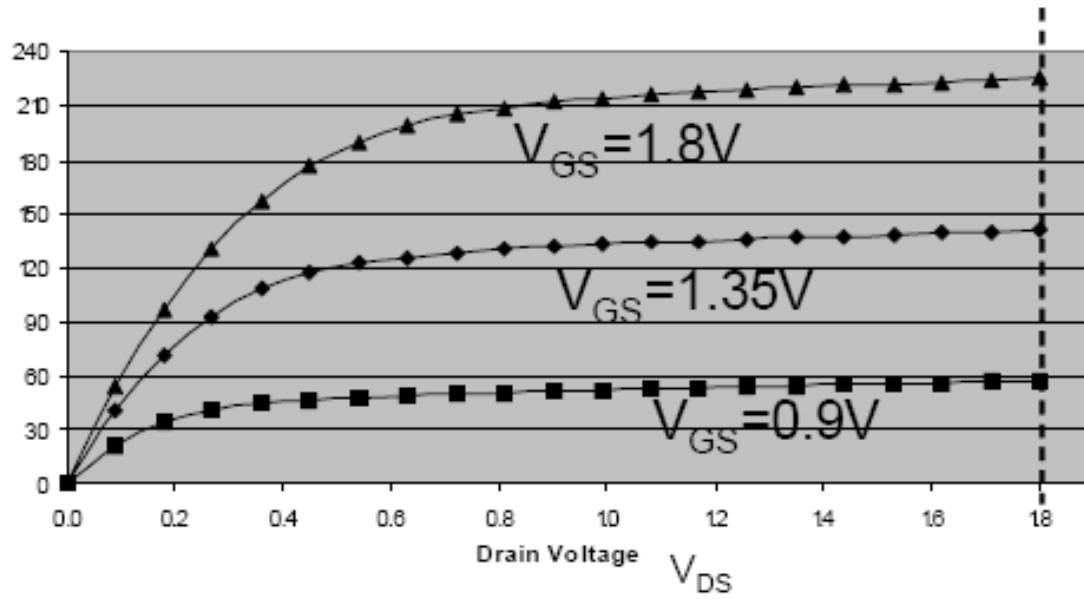


Current-Voltage Relations

The Deep-Submicron Era

- The quadratic model is valid for long channel devices
- In DSM, channel length is scaled
 - Vertical and horizontal electric fields are large and they interact with each other
 - Saturation in DSM devices occur when the carriers reach velocity saturation

I_{DS} vs. V_{DS} for NMOS



Effect of high fields

1980:	1995:	2001:
$E_y = \frac{5V}{5\mu m} = 10^4 V/cm$	$E_y = \frac{3.3V}{0.35\mu m} = 9.4 \times 10^4 V/cm$	$E_y = \frac{1.2V}{0.1\mu m} = 1.2 \times 10^5 V/cm$

Horizontal Field

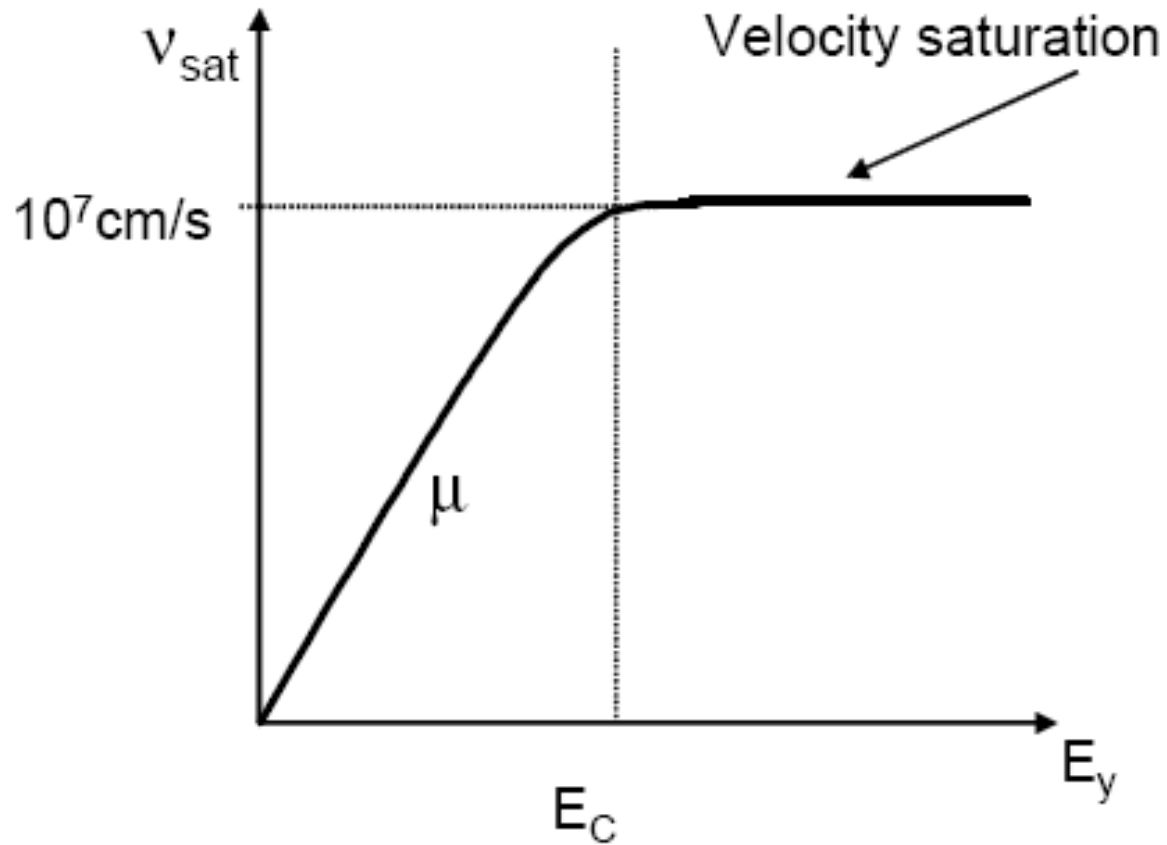
1980:	1995:	2001:
$E_x = \frac{5V}{1000\text{\AA}} = 50 \times 10^4 V/cm$	$E_x = \frac{3.3V}{100\text{\AA}} = 4.4 \times 10^6 V/cm$	$E_x = \frac{1.2V}{22\text{\AA}} = 5.5 \times 10^6 V/cm$

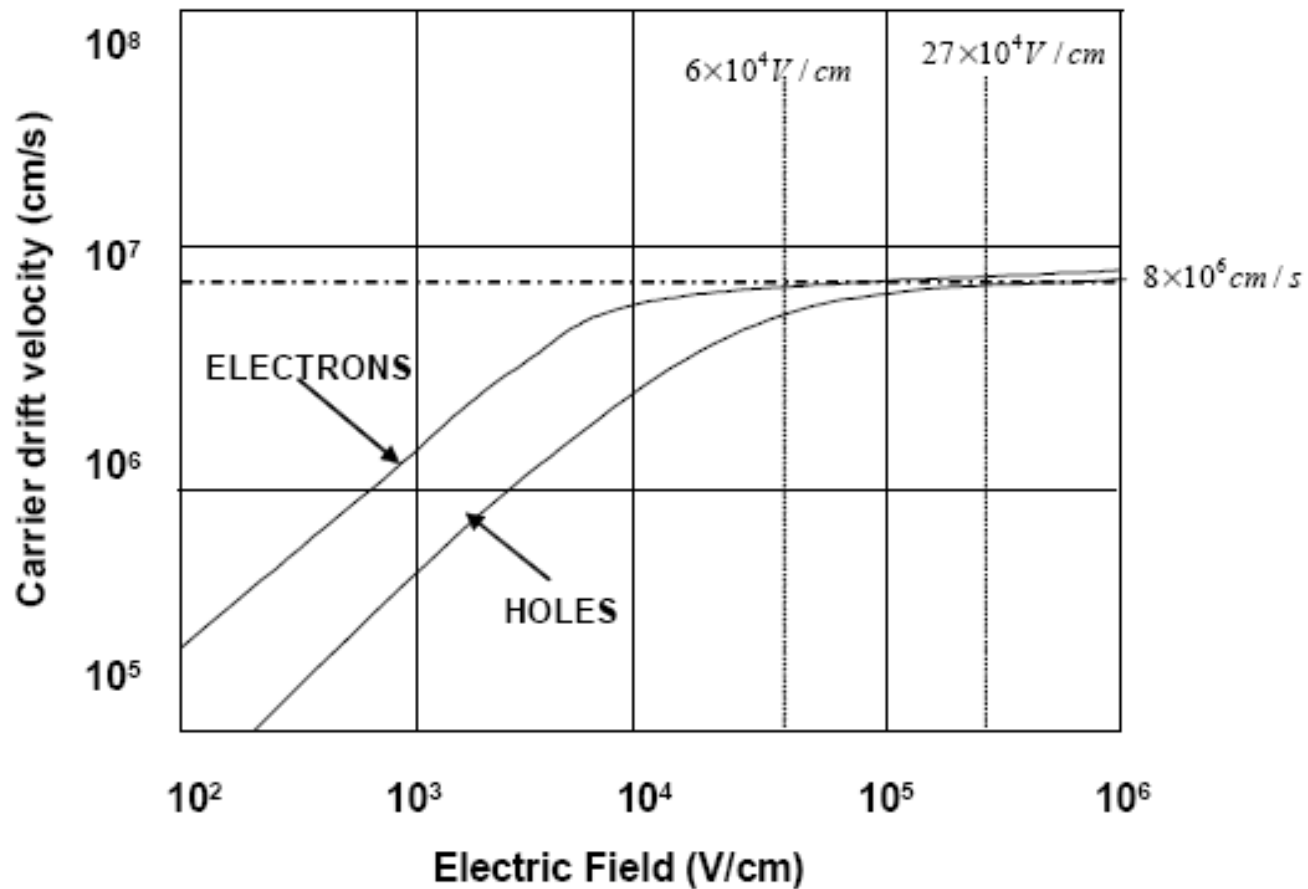
Vertical Field

Effect of high fields (Cont'd)

- Effect of the vertical field on the mobility
 - The vertical field increases the electron scattering at the surface of the channel
- Follow board notes
- The horizontal field acts to reduce the mobility even further

Velocity Saturation





$$E_{cn} = 6 \times 10^4 \frac{\text{V}}{\text{cm}} \text{ for electrons}$$

$$E_{cp} = 27 \times 10^4 \frac{\text{V}}{\text{cm}} \text{ for hole.}$$

Velocity Saturation (Cont'd)

$$v = \mu_e \frac{E}{\left(1 + \frac{E}{E_c}\right)} \quad E_y < E_c$$

$$v = v_{sat} \quad E_y \geq E_c$$

$$v = \mu_e \frac{E}{\left(1 + \frac{E}{E_c}\right)} = \frac{\mu_e E_c}{2}$$

$$\therefore E_c = \frac{2 v_{sat}}{\mu_e}$$

Current Equations

$$I_{DS} = W \times Q_n \times v$$

$$I_{DS} = W C_{ox} (V_{GS} - V_T - V(y)) \left(\frac{\mu_e E}{1 + \frac{E}{Ec}} \right)$$

$$I_{DS} = \frac{W}{1 + \frac{E}{Ec}} C_{ox} (V_{GS} - V_T - V(y)) \mu_e E$$

where $E = -\frac{dV(y)}{dy}$

Current Equation (Cont'd)

$$I_{DS} = W\mu_s \left[C_{ox}(V_{GS} - V_T - V(y)) + \frac{I_{DS}}{W/\mu_s E} \right] \frac{dV(y)}{dy}$$

$$I_{DS} = \frac{W}{L} \cdot \frac{\mu_s C_{ox}}{\left(1 + \frac{V_{DS}}{E_c L}\right)} \left(V_{GS} - V_T - \frac{V_{DS}}{2}\right) V_{DS}$$

Current Equation (Saturation)

$$I_{DS} = W \times Q_n \times v_{sat}$$

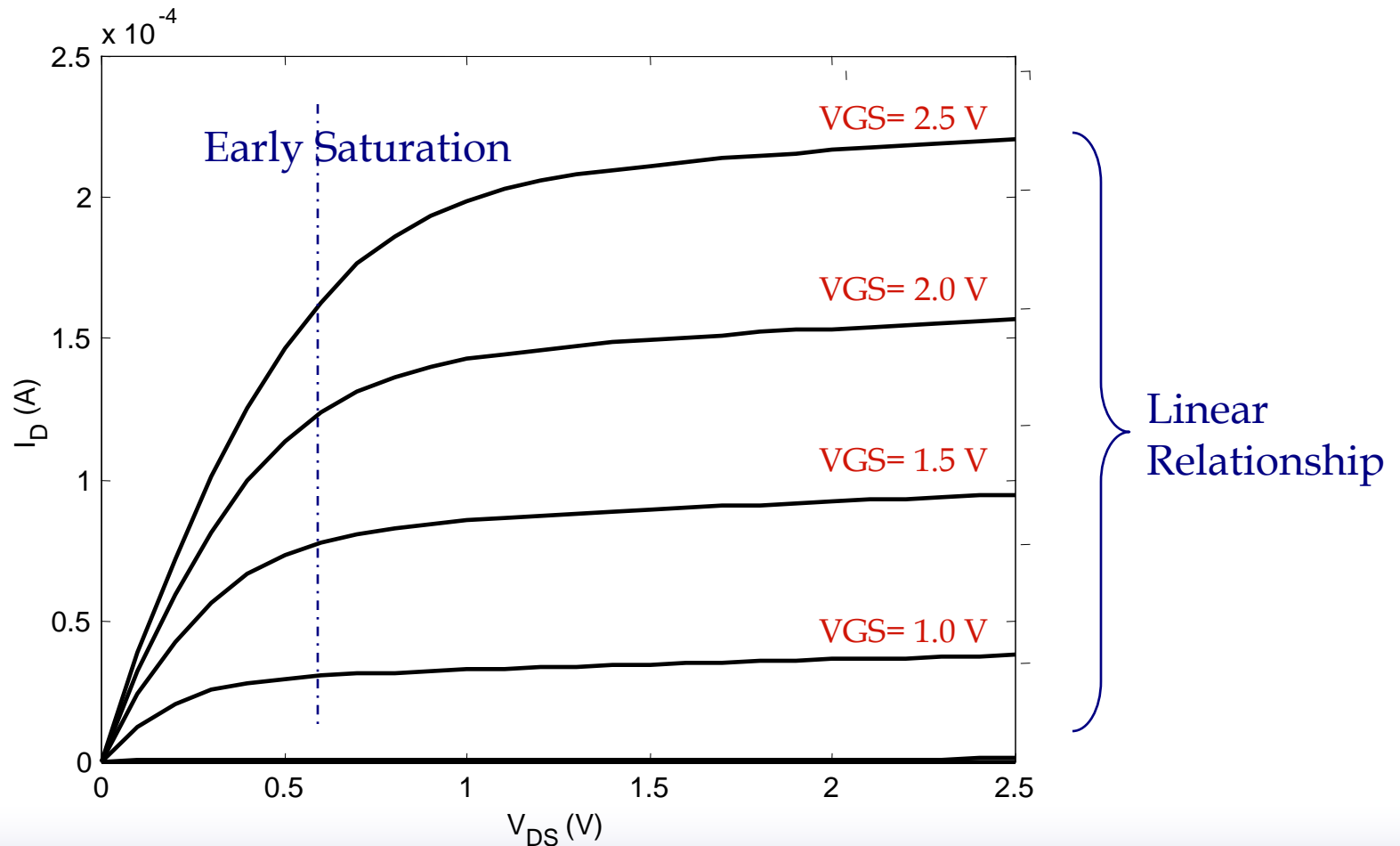
$$I_{DS} = W \times C_{ox} (V_{GS} - V_T - V_{DS}) v_{sat}$$

$$V_{Dsat} = \frac{(V_{GS} - V_T) E_c L}{(V_{GS} - V_T) + E_c L}$$

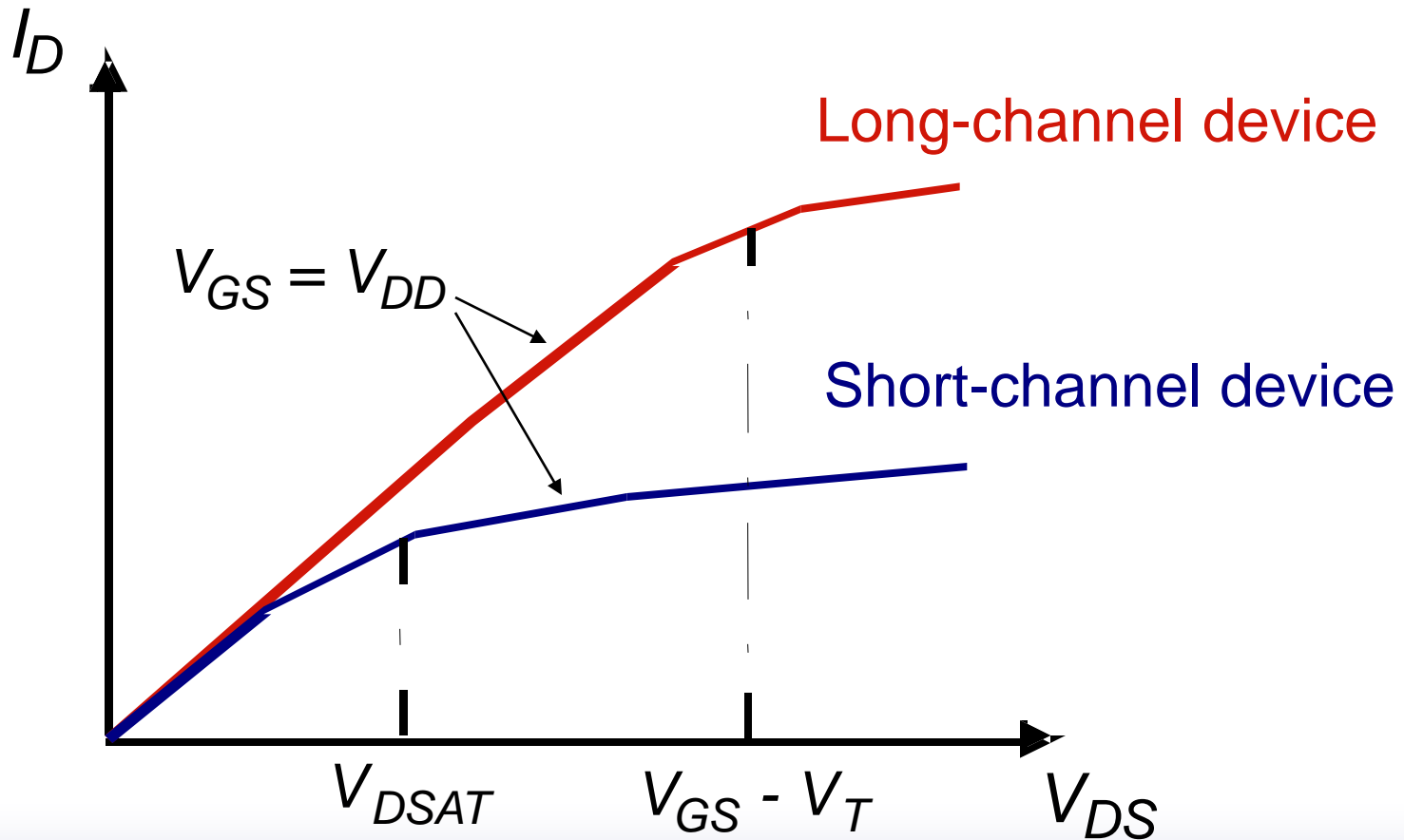
$$I_{DS} = W v_{sat} C_{ox} \frac{(V_{GS} - V_T)^2}{(V_{GS} - V_T) + E_c L}$$

Current-Voltage Relations

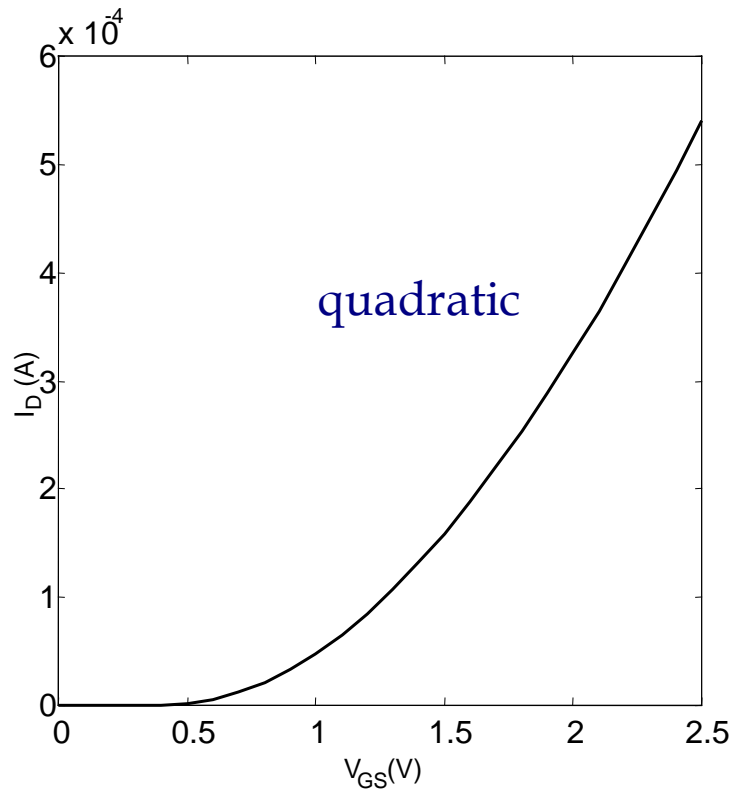
The Deep-Submicron Era



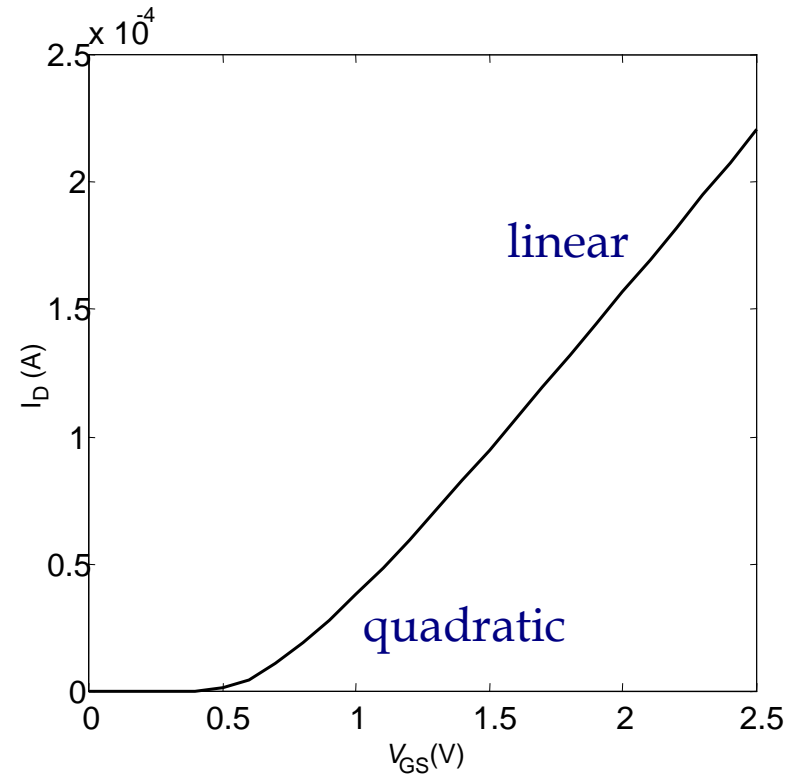
Perspective



I_D versus V_{GS}

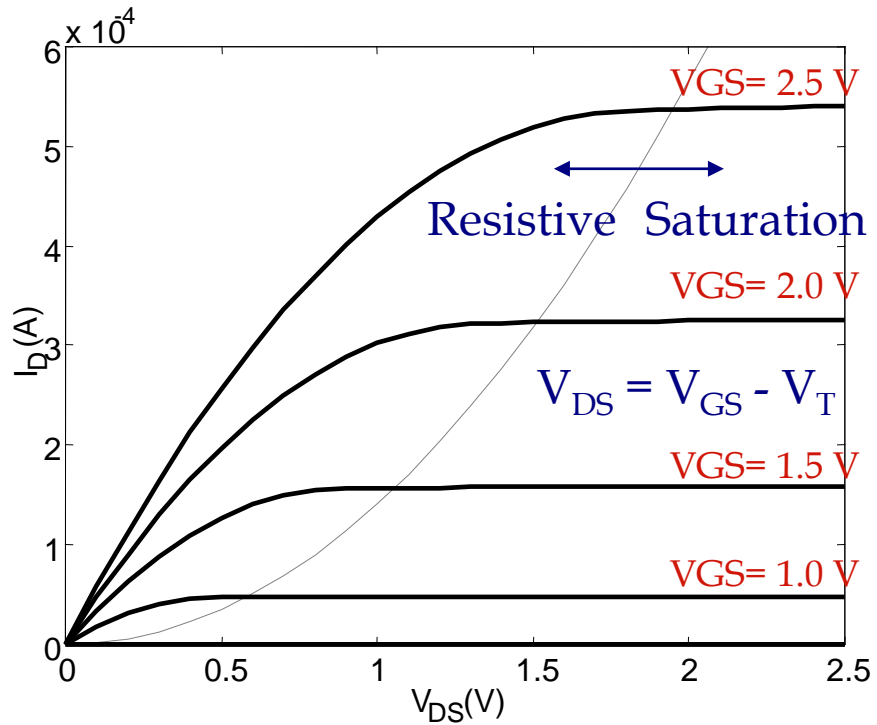


Long Channel

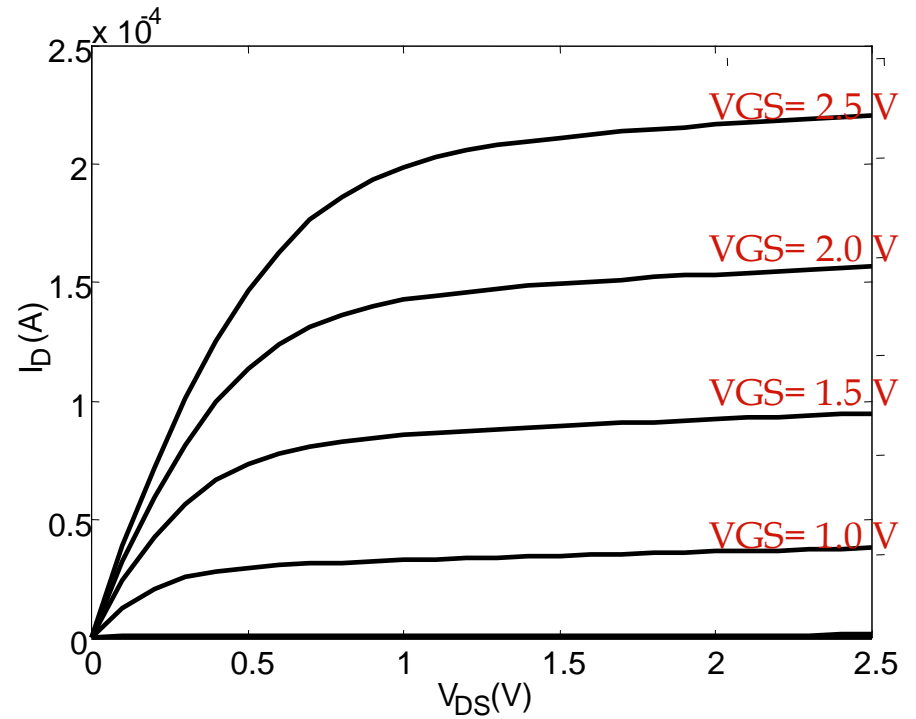


Short Channel

I_D versus V_{DS}

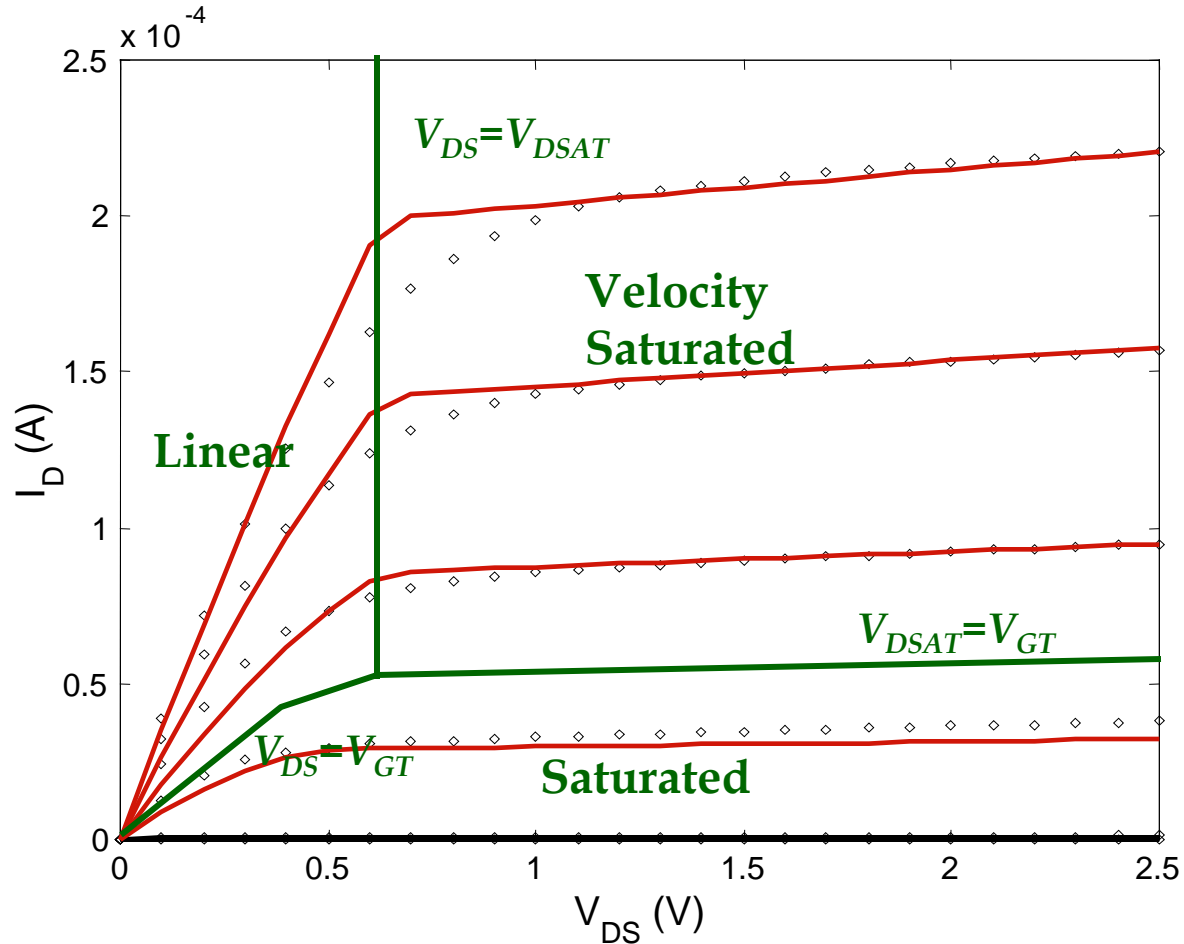


Long Channel

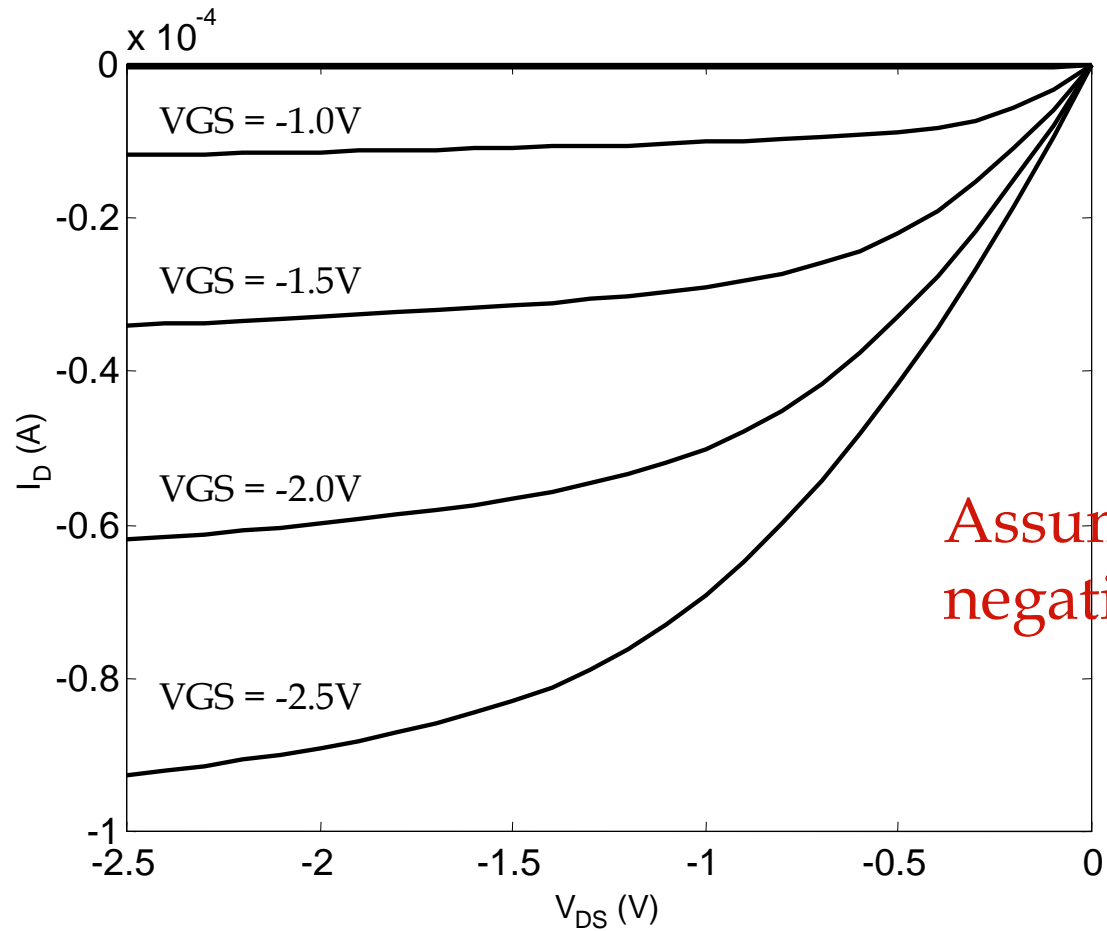


Short Channel

Simple Model versus SPICE



A PMOS Transistor



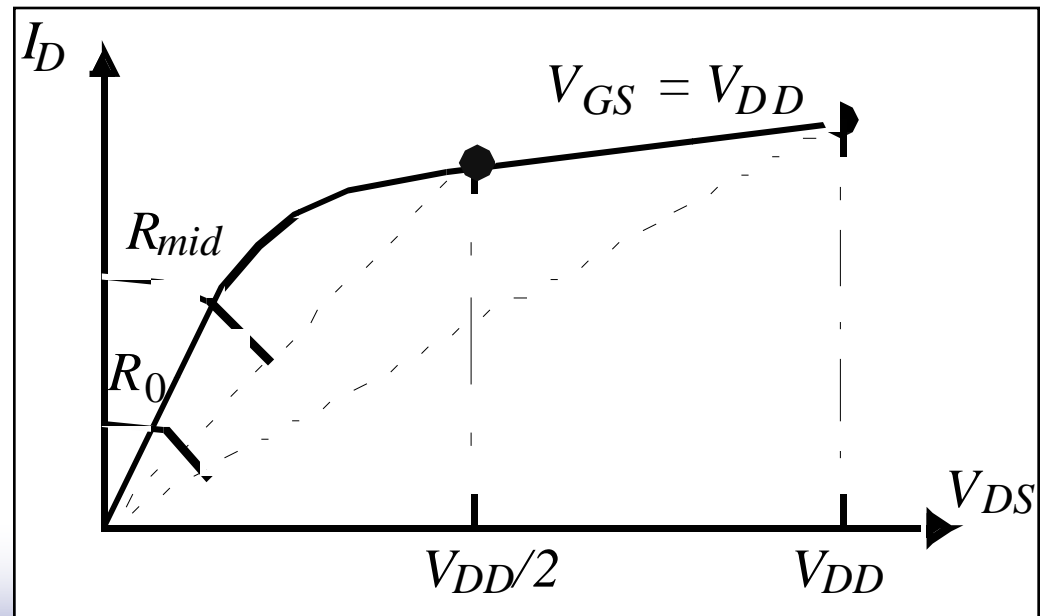
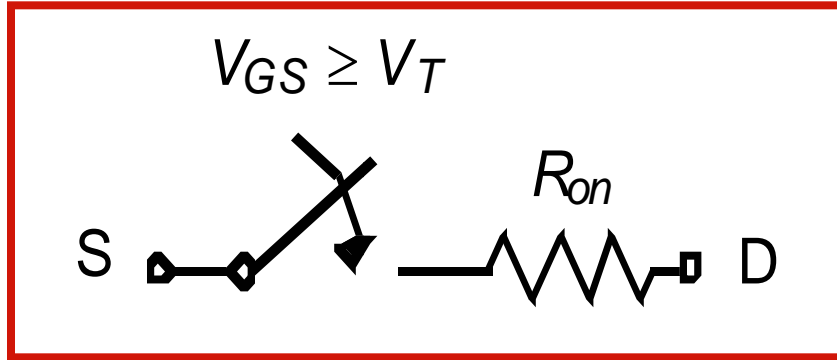
Assume all variables negative!

Transistor Model for Manual Analysis

Table 3.2 Parameters for manual model of generic 0.25 μm CMOS process (minimum length device).

	V_{T0} (V)	γ ($\text{V}^{0.5}$)	V_{DSAT} (V)	k' (A/V^2)	λ (V^{-1})
NMOS	0.43	0.4	0.63	115×10^{-6}	0.06
PMOS	-0.4	-0.4	-1	-30×10^{-6}	-0.1

The Transistor as a Switch



The Transistor as a Switch

Table 3.3 Equivalent resistance R_{eq} ($W/L=1$) of NMOS and PMOS transistors in 0.25 μm CMOS process (with $L = L_{min}$). For larger devices, divide R_{eq} by W/L .

V_{DD} (V)	1	1.5	2	2.5
NMOS (k Ω)	35	19	15	13
PMOS (k Ω)	115	55	38	31